



Materials Declaration Form


IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2019-07-05
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	MDG MD CHAMPION	Representative Title	MDG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement	
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Legal Statement	
Supplier Acceptance *	true
Legal Declaration *	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32F765IGT6	Y71T*451XXX1	D	9991	2019-07-05
	Amount	UoM	Unit type	ST ECOPACK Grade
	1649.98	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable; if coating is used or other bulk termination	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
LQFP	24x24x1.4	176		
Comment	Package : 1T LQFP 176 24x24x1.4 0110489			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-27th June 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration :						Mfr Item Name	Y71T*451XXX1				5000000.0	1016908.0
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	29.874	mg	supplier	die	Silicon (Si)	7440-21-3		28.292	mg	947044	17147
				supplier	metallization	Aluminium (Al)	7429-90-5		0.111	mg	3716	67
				supplier	metallization	Copper (Cu)	7440-50-8		0.719	mg	24068	436
				supplier	metallization	Cobalt (Co)	7440-48-4		0.002	mg	67	1
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.100	mg	3347	61
				supplier	metallization	Tungsten (W)	7440-33-7		0.323	mg	10812	196
				supplier	Passivation	Silicon Nitride	12033-89-5		0.084	mg	2812	51
Leadframe LF# A21299-0		526.000	mg	supplier	Passivation	Silicon Oxide	7631-86-9		0.243	mg	8134	147
					Leadframe	Copper (Cu)	7440-50-8		496.018	mg	943000	305035
					Leadframe	Nickel (Ni)	7440-02-0		16.832	mg	32000	10351
					Leadframe	Silicon (Si)	7440-21-3		3.814	mg	7250	2345
					Leadframe	Magnesium (Mg)	7439-95-4		0.921	mg	1750	566
					Leadframe	Silver (Ag)	7440-22-4		8.416	mg	16000	5176
					Bonding wire	Au	7440-57-5		3.366	mg	990000	2078
Bonding wire (Au 0.8 mils)		3.400	mg		Bonding wire	Pd	7440-05-3		0.034	mg	10000	21
					Bonding wire							
Encapsulation (Sumitomo,EME-G631H)		1072.000	mg		Molding Compound	Epoxy Resin A	Proprietary		26.800	mg	25000	16542
					Molding Compound	Epoxy Resin B	Proprietary		26.800	mg	25000	16542
					Molding Compound	Phenol Resin	Proprietary		48.240	mg	45000	29776
					Molding Compound	Silica(Amorphous) A	60676-86-0		838.304	mg	782000	517440
					Molding Compound	Silica(Amorphous) B	7631-86-9		128.640	mg	120000	79403
					Molding Compound	Carbon Black	1333-86-4		3.216	mg	3000	1985
External Plating		18.700	mg		Matte Sn	Tin (Sn)	7440-31-5		18.698	mg	999900	11541
					Matte Sn	Impurities	Proprietary		0.002	mg	100	1